

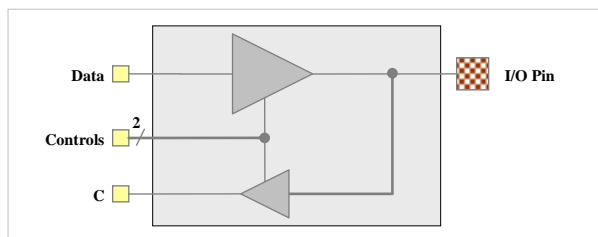
## Libraries

Name	Process	Form Factor	Silicon proven
RGO_GF28_18V33_SLP_20C_PCI	SLP	staggered	yes
RGO_GF28_18V33_SLP_40C_PCI	SLP	Inline	yes
RGO_GF28_18V33_HPP_20C_PCI	HPP	staggered	4Q11
RGO_GF28_18V33_HPP_40C_PCI	HPP	Inline	4Q11

## Summary

These pads are compatible with PCI Local Bus Specification Revision 3.0 for 3.3V signaling. Cell can be used for both 33MHz and 66MHz operation.

## PCx\_BI\_066\_33V\_NCW



## Description

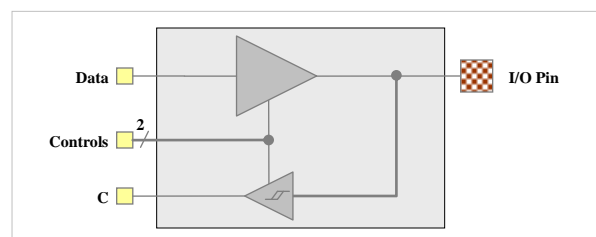
PCI 3.0 pad without Schmitt trigger.

## ESD Protection

I/O pads are designed with robust ESD protection for all market segments. Passed:

- 2KV ESD Human Body Model (HBM)
- 200 V ESD Machine Model (MM)
- 500 V ESD Charge Device Model (CDM)

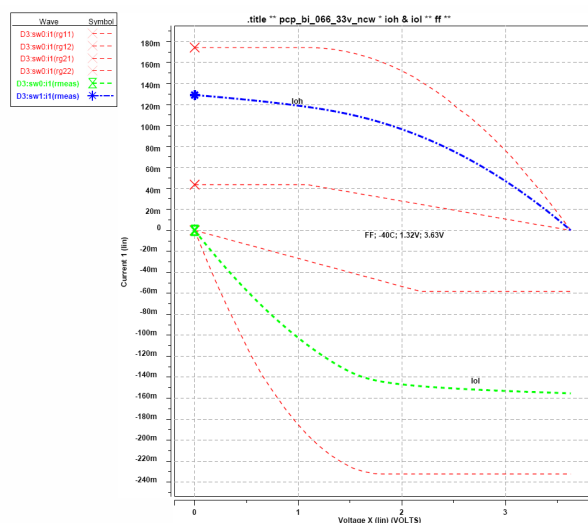
## PCx\_BI\_066\_33V\_SCW



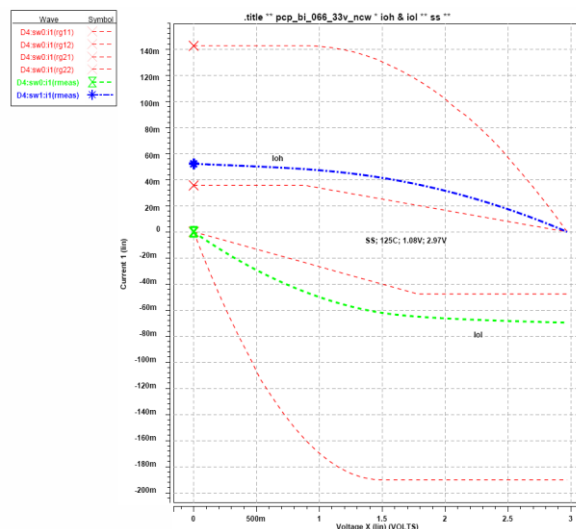
## Description

PCI 3.0 pad with Schmitt trigger.

## IOH / IOL (FF corner)



## IOH / IOL (SS corner)



## Recommended operating conditions

Description	Min	Nom	Max	Units
V <sub>DVDD</sub> I/O supply voltage	2.97	3.3	3.63	V
T <sub>A</sub> Ambient operating temperature	0	25	100	°C
V <sub>VDD</sub> Core supply voltage	0.9	1.0-1.1	1.15	V
T <sub>J</sub> Junction temperature	-40	25	125	°C
V <sub>PAD</sub> Voltage at PAD	0	-	V <sub>DVDD</sub>	V
V <sub>IH</sub> Input logic high	0.7 * V <sub>DVDD</sub>		V <sub>DVDD</sub> + 0.3	V
V <sub>IL</sub> Input logic low	V <sub>DVSS</sub> - 0.3		0.3 * V <sub>DVDD</sub>	V

## Characterization Corners

Nominal VDD	Model	VDD	DVDD = 3.3V	Temperature
1.1 <sup>[1]</sup>	FF	+5%	+10%	-40°C
	FF	+5%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C
1.0 <sup>[1]</sup>	FF	+10%	+10%	-40°C
	FF	+10%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C
0.85 <sup>[2]</sup>	FF	+10%	+10%	-40°C
	FF	+10%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C

<sup>[1]</sup> SLP process only

<sup>[2]</sup> HPP process only

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